

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Currently Amended) A surface acoustic wave device comprising:

a surface acoustic wave element having a first surface on which an electrode is formed;

a mounting substrate having an electrode on a surface and disposed facing the first surface with a gap of a predetermined distance sandwiched therebetween;

a bump for coupling the electrode on the surface acoustic wave element and the electrode on the mounting substrate to each other; and

a sealing resin formed on the mounting substrate so as to cover the surface acoustic wave element;

wherein the sealing resin comprises

a first resin surrounding the surface acoustic wave element and covering the mounting substrate on a periphery of the surface acoustic wave element,

a second resin covering at least the first resin, and

a third resin covering at least the second resin,

in which the third resin has an elastic modulus that is lower than an elastic modulus of the second resin and that is higher than an elastic modulus of the first resin,

wherein a thickness of the first resin formed on a side surface of the surface acoustic wave element is 1/10 to 1/2 of the distance of the gap.

2. (Cancelled)
3. (Cancelled)
4. (Previously Presented) The surface acoustic wave device of claim 1,

wherein at least the second resin in the sealing resin further intervenes in a part of the gap between the surface acoustic wave element and the mounting substrate.

5. (Original) The surface acoustic wave device of claim 4,

wherein the second resin is a resin filled with filler.

6. (Original) The surface acoustic wave device of claim 5,

wherein the filler comprises filler having a diameter that is 40% or more of the distance of the gap.

7. (Previously Presented) The surface acoustic wave device of claim 1,

wherein the second resin and the third resin are not brought into direct contact with the mounting substrate.

8. (Previously Presented) The surface acoustic wave device of claim 1,

wherein the second resin is brought into contact with the mounting substrate via the first resin and the third resin is brought into contact with the mounting substrate via the first resin or the second resin.

9. (Currently Amended) A surface acoustic wave device comprising:

a surface acoustic wave element and a mounting substrate, which are disposed in such a manner in which a surface of an excitation portion of the surface acoustic wave element faces an upper surface of the mounting substrate;

a pad electrode on the surface acoustic wave element and a pad electrode on the mounting substrate both being fixed with a bump so that they are electrically coupled to each other; and

an upper surface of the mounting substrate being sealed with sealing resin so as to cover the surface acoustic wave element in a state in which vibration space is secured between the excitation portion of the surface acoustic wave element and the mounting substrate;

wherein the sealing resin has at least three-layered structure including,

a first resin covering a rear surface and a side surface of the surface acoustic wave element and at least a part of the upper surface of the mounting substrate,

a second resin covering at least the first resin, and

a third resin covering at least the second resin,

in which the second resin has an elastic modulus that is higher than an elastic modulus of the third resin and the first resin has an elastic modulus that is lower than an elastic modulus of the third resin,

wherein at least the second resin exists in a part of space between the surface acoustic wave element and the mounting substrate.

10. (Cancelled)

11. (Original) The surface acoustic wave device of claim 1, wherein the elastic modulus of the third resin is not lower than 5 GPa and not higher than 10 GPa.

12. (New) A surface acoustic wave device comprising:

a surface acoustic wave element having a first surface on which an electrode is formed;

a mounting substrate having an electrode on a surface and disposed facing the first surface with a gap of a predetermined distance sandwiched therebetween;

a bump for coupling the electrode on the surface acoustic wave element and the electrode on the mounting substrate to each other; and

a sealing resin formed on the mounting substrate so as to cover the surface acoustic wave element;

wherein the sealing resin comprises

a first resin surrounding the surface acoustic wave element and covering the mounting substrate on a periphery of the surface acoustic wave element,

a second resin covering at least the first resin, and

a third resin covering at least the second resin,

in which the third resin has an elastic modulus that is lower than an elastic modulus of the second resin and that is higher than an elastic modulus of the first resin,

wherein at least the second resin in the sealing resin further intervenes in a part of the gap between the surface acoustic wave element and the mounting substrate.

13. (New) The surface acoustic wave device of claim 12,

wherein the second resin is a resin filled with filler.

14. (New) The surface acoustic wave device of claim 13,

wherein the filler comprises filler having a diameter that is 40% or more of the distance of the gap.

15. (New) The surface acoustic wave device of claim 12,

wherein the second resin and the third resin are not brought into direct contact with the mounting substrate.

16. (New) The surface acoustic wave device of claim 12,

wherein the second resin is brought into contact with the mounting substrate via the first resin and the third resin is brought into contact with the mounting substrate via the first resin or the second resin.

17. (New) A surface acoustic wave device comprising:

a surface acoustic wave element having a first surface on which an electrode is formed;

a mounting substrate having an electrode on a surface and disposed facing the first surface with a gap of a predetermined distance sandwiched therebetween;

a bump for coupling the electrode on the surface acoustic wave element and the electrode on the mounting substrate to each other; and

a sealing resin formed on the mounting substrate so as to cover the surface acoustic wave element;

wherein the sealing resin comprises

a first resin surrounding the surface acoustic wave element and covering the mounting substrate on a periphery of the surface acoustic wave element,

a second resin covering at least the first resin, and

a third resin covering at least the second resin,

in which the third resin has an elastic modulus that is lower than an elastic modulus of the second resin and that is higher than an elastic modulus of the first resin,

wherein the second resin and the third resin are not brought into direct contact with the mounting substrate.

18. (New) The surface acoustic wave device of claim 17,

wherein the second resin is brought into contact with the mounting substrate via the first resin and the third resin is brought into contact with the mounting substrate via the first resin or the second resin.

19. (New) A surface acoustic wave device comprising:

a surface acoustic wave element having a first surface on which an electrode is formed;

a mounting substrate having an electrode on a surface and disposed facing the first surface with a gap of a predetermined distance sandwiched therebetween;

a bump for coupling the electrode on the surface acoustic wave element and the electrode on the mounting substrate to each other; and

a sealing resin formed on the mounting substrate so as to cover the surface acoustic wave element;

wherein the sealing resin comprises

a first resin surrounding the surface acoustic wave element and covering the mounting substrate on a periphery of the surface acoustic wave element,

a second resin covering at least the first resin, and

a third resin covering at least the second resin,

in which the third resin has an elastic modulus that is lower than an elastic modulus of the second resin and that is higher than an elastic modulus of the first resin,

wherein the second resin is brought into contact with the mounting substrate via the first resin and the third resin is brought into contact with the mounting substrate via the first resin or the second resin.